ABSTRACT OF THE DISCLOSURE

This is to present a mounting method of semiconductor element capable of joining an electrode of a semiconductor element and a circuit of a circuit board at high reliability.

It comprises a step of forming an external electrode terminal 33 by filling a hole 8 formed in a circuit board 4 with a conductive paste 7, a step of positioning the external electrode terminal 33 and a protruding bump 3 formed on an electrode 2 of a semiconductor 1, and a step of pressing the semiconductor element 1 to contact between the conductive paste 7 in the hole 8 and the protruding bump 3, thereby electrically connecting the electrode 2 of the semiconductor element 1 and the external electrode terminal 33 of the circuit board 4.